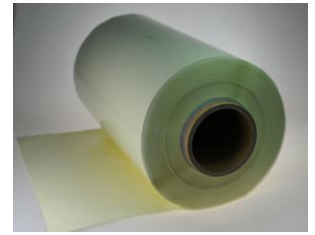




## Thermally Conductive adhesive tape

### Product Description

This tape is specially developed to provide an effective thermal interface and heat sink attachment method for plastic component packages



### Features

- Hi-bonding strength, specially made for ceramic heat sink, or heat sink with rough surface.
- Double side adhesive, high bonding strength, great insulation, easy to use.
- Able to be die cut or form into shape for label or stickers.

### Applications

- Assembly of the heat sink and DDR-RAM module.
- Assembly of the LED light bar module and metal frame bezel.
- Die-cut piece and Laminate.

### Storage and Shelf Life

- Store in original cartons at 23±5°C and 60%±10% relative humidity in order to obtain best performance, besides use these products within 15 months from date of manufacture.



### SPECIFICATION

Physical Properties	Unit	SF-TC015R	Test Method
Color	-	White	-
Thickness	mm	0.15±0.03	Internal
Carrier	-	Non-woven polyester film	-
Peel Adhesion			
Room Temp Dwell @ 20 min	Kg/25mm	1.6	PSTC-3
65°C Dwell @20min		1.8	
Room Temp Dwell @ 72 hrs		1.8	
65°C Dwell @72 hrs		2.0	
Shear Strength	Hours	Over 48	PSTC-7
1.0kg loading on 25mm x 25mm			
Heat Resistance	Hours	Over 24	PSTC-7
0.5kg loading on 25mm x 25mm at 60°C			
Service Temperature	°C	-30~120	Internal
Thermal impedance coefficient	°C-in <sup>2</sup> /w	0.1	ASTM D5470
Thermal Conductivity	w/m-K	2.4	ASTM D5470